

Advanced Packaging Update: Market and Technology Trends

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This issue of the Advanced Packaging Update provides an analysis of the impact of AI demand on the supply chain including HBM, build-up substrates, and substrate materials. A supply and demand analysis reveals a potential build-up substrate shortage starting in 2027. A progress report on hybrid bonding for a variety of applications is presented and alternatives for 3D stacking are discussed. OSAT financials are provided.

Table of Contents

1 Industry and Economic Trends

- 1.1 Economic Growth Slows
 - 1.1.1 China's Economy
 - 1.1.2 U.S. Macroeconomic Trends
- 1.2 Smartphone and PC Growth
 - 1.2.1 PC Shipments
 - 1.2.2 Smartphone Shipments
 - 1.2.3 AI Continues to Drive Industry Growth

2 OSAT Financial Analysis

- 2.1 Market Overview
- 2.2 OSAT Market Performance
- 2.3 Company Highlights
 - 2.3.1 ASE Holdings
 - 2.3.2 Amkor Technology
 - 2.3.3 JCET Group
 - 2.3.4 Tongfu Microelectronics
 - 2.3.5 Powertech Technology
 - 2.3.6 Huatian
 - 2.3.7 UTAC
 - 2.3.8 KYEC
 - 2.3.9 Hana Micron
 - 2.3.10 ChipMOS
- 2.4 Financial Metrics
 - 2.4.1 Gross Margin
 - 2.4.2 R&D
 - 2.4.3 CAPEX
- 2.5 Outlook

3 Will Shortages Limit AI Growth?

- 3.1 Growing Demand for AI Hardware
 - 3.1.1 Demand for Substrates
 - 3.1.1.1 BT Resin
 - 3.1.1.2 Glass Fiber
 - 3.1.1.3 Build-up Film
 - 3.1.2 HBM

4 Hybrid Bonding Developments

- 4.1 Applications
 - 4.1.1 Computing
 - 4.1.1.1 AMD
 - 4.1.1.2 Broadcom
 - 4.1.1.3 Intel

- 4.1.2 High Bandwidth Memory
- 4.1.3 Co-packaged Optics
- 4.1.4 6G Communications
- 4.1.5 Finer Pitch for Future Applications
- 4.2 Hybrid Bonding Challenges
 - 4.2.1 Design and EDA Tools
 - 4.2.2 Process
 - 4.2.2.1 Cu Recess Control and Dielectric
 - 4.2.2.2 Low-Temperature Processing
 - 4.2.3 Metrology
- 4.3 Hybrid Bonding Equipment
 - 4.3.1 Applied Materials and BESi
 - 4.3.2 ASMP
 - 4.3.3 Bondtech
 - 4.3.4 EV Group
 - 4.3.5 Hanmi
 - 4.3.6 SET
 - 4.3.7 SUSS
 - 4.3.8 TEL
 - 4.3.9 Toray Engineering
 - 4.3.10 Room Temperature Bonding
- 4.4 Alternatives to Hybrid Bonding
 - 4.4.1 ASMP
 - 4.4.2 K&S
 - 4.4.3 Shibuya

List of Figures

- 4.1. Collective bonding process.

Partial List of Tables

- 2.1. Quarterly Revenue for Top 20 OSATs
- 2.2. Year-to-Year Gross Margin for Top 10 OSATs
- 2.3. R&D Spending for Top 10 OSATs
- 2.4. CAPEX Spending for Top 10 OSATs
- 3.1. Build-up Substrate Supply and Demand
- 3.2. HBM Demand Forecast
- 4.1. Hybrid Bonders
- 4.2. D2W vs. W2W
- 4.3. Hybrid Bonding vs. Direct TCB
- 4.4. Fluxless Bonders for TCB


TechSearch
INTERNATIONAL

4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759

Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com

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